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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/765,772	01/26/2004	Gabe Cherian		2451
39574	7590	03/01/2006		
GABE CHERIAN P.O. BOX 1335 SUN VALLEY, ID 83353			EXAMINER NGUYEN, HOA CAO	
			ART UNIT 2841	PAPER NUMBER

DATE MAILED: 03/01/2006

Please find below and/or attached an Office communication concerning this application or proceeding.



**DETAILED ACTION**

***Election/Restrictions***

1. Restriction to one of the following inventions is required under 35 U.S.C. 121:
  - I. Claims 1-6, drawn to a structure of a solder pad, classified in class 174, subclass 138G.
  - II. Claims 7-11, drawn to a structure of a solder joint, classified in class 228, subclass 4.1 plus.
  - III. Claims 12-19, drawn to a method of creating an assembly for a joining mean, classified in class 29, subclass 830 plus.
  - IV. Claims 20-21, drawn to a structure of a lead frame, classified in class 361, subclass 723 plus.
2. The inventions are distinct, each from the other because of the following reasons:
3. Inventions III and I are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make other and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). In the instant case the product as claimed could be formed by not using a solder joint but by conductive adhesive glue instead soldering.

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4. Inventions III and II are related as process of making and product made. The inventions are distinct if either or both of the following can be shown: (1) that the process as claimed can be used to make other and materially different product or (2) that the product as claimed can be made by another and materially different process (MPEP § 806.05(f)). In the instant case the product as claimed can be formed by not using a spacer between the device and the printed circuit board but by a precise setting and compressing (between an electronic device and a PCB) during soldering process.

5. Inventions III and IV are unrelated. Inventions are unrelated if it can be shown that they are not disclosed as capable of use together and they have different designs, modes of operation, and effects (MPEP § 802.01 and § 806.06). In the instant case, the different inventions between the Invention III and IV are as followings:

(a) Invention III drawn to a method of soldering an electronic device on a surface of a PCB (a surface mounting process).

(b) Invention IV drawn to a structure of a lead frame, which is clearly unrelated to the process of soldering in the Invention III.

6. Inventions IV and I are unrelated. Inventions are unrelated if it can be shown that they are not disclosed as capable of use together and they have different designs, modes of operation, and effects (MPEP § 802.01 and § 806.06). In the instant case, the different inventions between the Invention IV and I are as followings:

(a) Invention IV drawn to a structure of a lead frame.

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(b) Invention I drawn to a structure of a solder pad.

Because the structure of the solder pad is totally independent from the structure of the lead frame, therefore both structures are not disclosed as capable of use together and they have different designs, modes of operation, and effects.

7. Inventions IV and II are unrelated. Inventions are unrelated if it can be shown that they are not disclosed as capable of use together and they have different designs, modes of operation, and effects (MPEP § 802.01 and § 806.06). In the instant case, the different inventions between the Invention IV and II are as followings.

(a) Invention IV drawn to a structure of a lead frame.

(b) Invention II drawn to a structure of a solder joint.

Because the structure of the solder joint is totally independent from the structure of the lead frame, therefore both structures are not disclosed as capable of use together and they have different designs, modes of operation, and effects.

8. Inventions I and II are related as subcombinations disclosed as usable together in a single combination. The subcombinations are distinct if they do not overlap in scope and are not obvious variants, and if it is shown that at least one subcombination is separately usable. In the instant case, invention II has separate utility such as the solder joint has a smaller cross-section at about the middle of tits height. See MPEP § 806.05(d).

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9. Because these inventions are distinct for the reasons given above and have acquired a separate status in the art as shown by their different classification, restriction for examination purposes as indicated is proper.

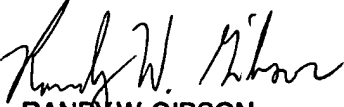
10. Applicant is advised that the reply to this requirement to be complete must include an election of the invention to be examined even though the requirement be traversed (37 CFR 1.143).

***Conclusion***

11. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Hoa C. Nguyen whose telephone number is 571-272-8293. The examiner can normally be reached on M-F.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Kammie Cuneo can be reached on 571-272-1957. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

  
RANDY W. GIBSON  
PRIMARY EXAMINER